



PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Shin-Fu WEI /

Attorney Docket No.: P66779US0

Serial No.: 09/883,227 /

Group Art Unit: 2841

Filed: June 19, 2001

Examiner: Tuan T. DINH

For: METAL HOUSING GROUNDING MECHANISM /

AMENDMENT

BOX NON-FEE AMENDMENT.
Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action of January 14, 2002
(Paper No. 2), please amend the above-captioned application as
follows:

IN THE ABSTRACT:

Please amend the Abstract of the Disclosure as follows:

--A metal housing grounding mechanism including a housing, a circuit board inside the housing and a connector is on one side of the circuit board. Two metal boards are on top and bottom of the connector. One of the metal boards is connected to ground. A spring tongue is on both ends of the two metal boards. The spring tongues of one metal board and the spring tongues of the other metal board brace together. Therefore the two metal boards are connected and conducted together for better shielding against electromagnetic waves and static electricity.

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IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Amended) A metal housing grounding mechanism comprising:

a housing;

a circuit board inside said housing,

a connector installed on one side of said circuit board;

two metal boards located on a top and a bottom of said connector respectively while one of said two metal boards being connectable to ground;

a spring tongue located on both ends of said two metal boards, said spring tongue being formed from a free end of said two metal boards,

said spring tongue of one of said two metal boards and said spring tongue of the other of said two metal boards forcibly engaging together with an opposing bias force so as to make the two metal boards connect and conduct together.

REMARKS

In the Office Action, claim 1 was rejected under 35 USC §102(b) as being anticipated by Farquhar et al.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version With Markings To Show Changes Made".

The present invention relates generally to a metal housing grounding mechanism which makes the metal boards of memory cards have a grounding structure in a most cost-effective and convenient way. The upper and lower metal boards hook with the folding part on the lateral side of the plastic plate. A spring tongue is disposed on both ends of the metal board. When the upper and lower metal boards are assembled with each other, the spring tongues on the metal boards are forcibly moved closely together so that the two metal boards are connected and conducted together for a better grounding connection.

As to the container for the memory cards recited in U.S. Patent No. 5,397,857, the upper and lower covers are secured to a plastic frame by fingers extending from the sides thereof. The plastic frame elements are injected molded around the fingers thus forming an integral unit. Then the two covers are welded together by sonic welding or glue.

When being manufactured, the bent edges of the metal covers are easy to deform in a horizontal plane under high temperature processing. Moreover, the two cover halves are then welded into an integral unit. The thickness of the place of welding increases the thickness of the unit so that the edges of the metal cover do not really contact with each other and only have low conductivity. Thus an improved grounding effect cannot be achieved.

As recited at column 3, lines 28-31, "The metal fingers 26 become embedded in the plastic frame elements 16 & 18 during the bonding and/or molding process to form an integral frame cover element." Therefore, the '857 patent does not have the claimed feature of the spring tongue being formed of a "free end". The fingers of the '857 patent are embedded in plastic and cannot move. Therefore, the claimed opposed bias engaging force of the spring tongues of the invention is not disclosed by the '857 patent.

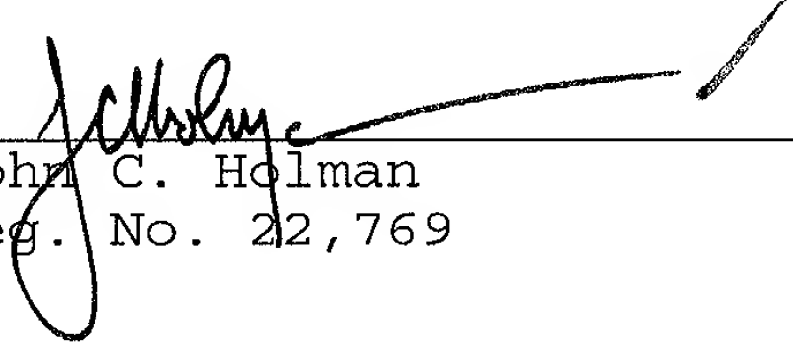
Based on the foregoing amendments and remarks, it is respectfully submitted that the claims in the present application, as they now stand, patentably distinguish over the references cited and applied by the Examiner and are, therefore, in condition for allowance. A Notice of Allowance is in order, and such favorable action and reconsideration are respectfully requested.

However, if after reviewing the above amendments and remarks, the Examiner has any questions or comments, he is cordially invited to contact the undersigned attorneys.

Respectfully submitted,

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By: _____


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